

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: R. IKEZAWA, et al.

Application No.: 10/552,441

Filed: OCTOBER 7, 2005

For: ENCAPSULATING EPOXY RESIN MOLDING MATERIAL, AND SEMICONDUCTOR DEVICE

Group AU: 2815

Examiner: Scott E. Bauman

Confirm. No.: 7255

AMENDMENT

Mail Stop: Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, Virginia 22313-1450

August 27, 2007

Sir:

In response to the Office Action mailed April 25, 2007, please amend the above-identified application as listed in the following, and as set forth on the following pages:

Amendments to the Claims; and

Remarks are included following the amendments.